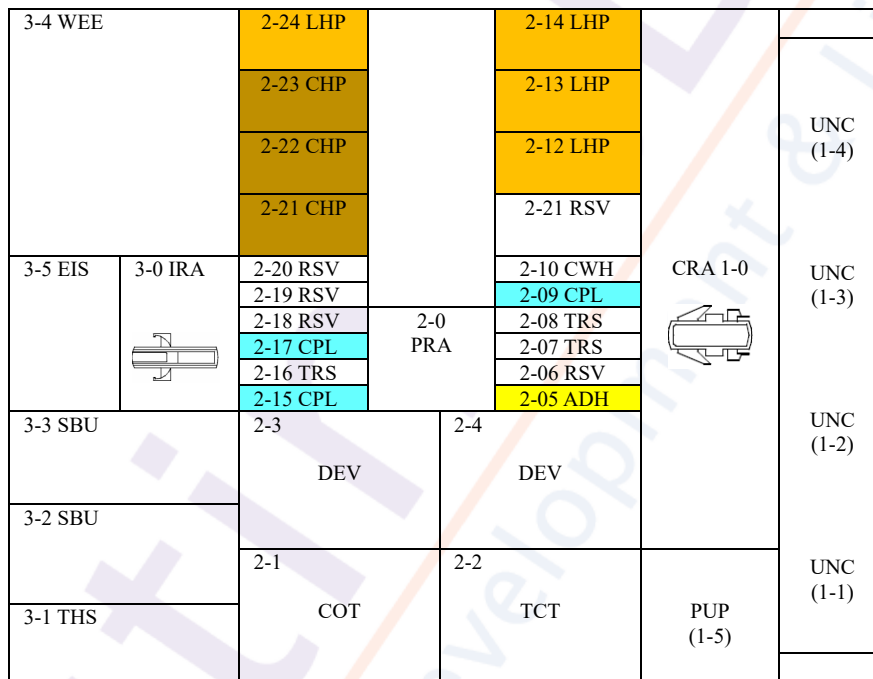


1. **Maker : TEL/Tokyo Electron Limited**
2. **Model : Clean Track ACT 8**
3. **Serial Number :**
4. **Vintage : 1998**
5. **Description : Photo Resist Coat and Develop System**
6. **Configuration**

1) **Block Diagram (Right to Left Wafer Flow)**

2,290 x 1,570 x 2,685 (L x W x H by mm)



Chemical Supply System

Develop, Solvent and HMDS Supply
 1,400 x 700 x 1,810 (L x W x H, mm)

Thermo Control Unit

INR-244-211D-45
 450 x 1,050 x 1,400 (L x W x H, mm)

AC Power Rack

600 x 600 x 2,000 (L x W x H, mm)

2) Chemical Cabinet Details

1 HMDS Canister 1G Tank Tray	2 2-5 ADH HMDS Buffer Tank Tray	3 Solvent Filter Tray	4 2-3DEV Filter Tray	5 2-4 DEV Filter Tray	6 2-2 TCT Filter Tray
7 Solvent 3L Buffer Tank 2ea			8 DEV 3L Buffer Tank 2ea		

3) Detailed Hardware Specification

- A. Wafer Size: 200mm, DUV/Deep UV Application, Single Block System
- B. Wafer Flow: Right to Left (CSB Unit is in Right side and Interface Station Unit is in Left side)
- C. Process Block: 1ea (Single Block System)
- D. Block #1 CSB
 - a. TEL Clean Track ACT 8 EC/Equipment Controller #2
 - b. Stage/Indexer: Open Uni-Cassette CSB/Cassette Stage Block
 - c. CRA/Cassette Block Robotics Arm: 1ea
 - d. FFU: N/A
- E. Block #2 PRB
 - a. 2-1 Standard Coat Unit : 8 Nozzle Exchange Type
 - ① 4 Standard Photo Resist Dispense Nozzles
 - ② 4 TEL OEM RRC F-T201 Photo Resist Pumps
 - ③ 1 Solvent Pre-wet RRC/Reduced Resist Coat Nozzle
 - ④ 1 Side Rinse Nozzle (Programmable Side Rinse EBR)
 - ⑤ Dual Back Rinse Nozzles
 - ⑥ Coat Cup Temperature Synchronized Control System
 - ⑦ Photo Resist Temperature Control
 - ⑧ Motor Flange Temperature Control
 - ⑨ Photo Resist Drain Type : Auto Drain (SMC Drain Pump Type)
 - ⑩ Auto Dummy Dispense System

⑪ Photo Resist Bottle Quantity :

	Resist #1	Resist #2	Resist #3	Resist #4
2-1	1 Bottle	1 Bottle	1 Bottle	1 Bottle
2-2	1 Bottle	1 Bottle	N/A	N/A

b. 2-2 TCT (Top ARC/Anti-Reflecting Coat) Unit

- ① 2 Standard Photo Resist Dispense Nozzles
- ② 2 TEL OEM RRC F-T201 Photo Resist Pumps
- ③ 1 Solvent Pre-wet RRC/Reduced Resist Coat Nozzle
- ④ 1 Side Rinse Nozzle (Programmable Side Rinse EBR)
- ⑤ Dual Back Rinse Nozzles
- ⑥ Coat Cup Temperature Synchronized Control System
- ⑦ Photo Resist Temperature Control
- ⑧ Motor Flange Temperature Control
- ⑨ Photo Resist Drain Type : Auto Drain (SMC Drain Pump Type)
- ⑩ Auto Dummy Dispense System
- ⑪ Photo Resist Bottle Quantity :

	Resist #1	Resist #2	Resist #3	Resist #4
2-1	1 Bottle	1 Bottle	1 Bottle	1 Bottle
2-2	1 Bottle	1 Bottle	N/A	N/A

c. 2-3 Develop Unit

- ① 1 Stream Nozzle
- ② Develop Temperature Control
- ③ Motor Flange Temperature Control
- ④ Drain Type : Direct Gravity Drain Type
- ⑤ Top Rinse Nozzle
- ⑥ Dual Back Rinse Nozzle
- ⑦ Auto Damper
- ⑧ Auto Dummy Dispense System

d. 2-4 Develop Unit : Same as 2-3 Develop Unit

e. PRA/Process Block Robotics Arm: 1ea

f. Plate Units

- A. ADH/Adhesion Process Station: 1ea
- B. LHP/Low Temperature Hot Plate Station: 4ea
- C. CPL/Chilling Plate Process Station: 3ea

- D. TRS/Transition Stage Unit: 3ea
- E. CHP/Chilling Hot Plate Process Station: 3ea
- F. CWH/Cup Washer Holder Unit: 1ea
- F. Block #3 IFB
 - a. IRA/Interface Robotics Arm : 1ea
 - b. Interface for ASML PAS5500/300C DUV Stepper
 - c. WEE/Wafer Edge Exposure Process Station : 1ea
 - d. THS/Temporary Holding Stage : 1ea
 - e. SBU/Stationary Buffer Unit : 2ea
 - f. TRS/Transition Stage Unit : N/A
 - g. CPL/Chill Plate Process Station : N/A
 - h. EIS/Interface Stage Module : N/A
 - i. FFU: Installed
- G. T&H/Temperature and Humidity Controller : N/A
- H. External Chemical Supply System/Cabinet (HMDS, Solvent, DEV Solutions)
 - a. HMDS Supply System
 - ① HMDS Chemical Type: 1ea
 - ② Manual Supply Type with 3 Liter Teflon Buffer Tanks (1)
 - ③ 1 Buffer Tank (3 Liter/Tank, Teflon, N2 Bubbling) for 1 ADH Unit
 - b. Solvent Supply System for 1 Standard COT (2-1) and 1 TCT (2-2)
 - ① Solvent Chemical Type: 1ea
 - ② Bulk-fill CSS/Central Chemical Supply Type with 3 Liter Teflon Buffer Tanks (2)
 - ③ 2 Buffer Tanks (3 Liter/Tank, Teflon) to support COT (2-1) and TCT (2-2)
 - c. Developer Supply System for 2 Develop Units (2-3 and 2-4)
 - ① Developer Chemical Type: 1ea
 - ② Bulk-Fill CSS/Central Chemical Supply Type with 3 Liter Teflon Buffer Tanks (2)
 - ③ 2 Buffer Tanks (3 Liter/Tank, Teflon) to support 2 Develop Units (2-3 and 2-4)
- I. TEL OEM TCU/Temperature Control Unit : 1ea
(SMC Circulator Pumps and Thermo Controller with 7 Channels)
 - a. 2 Chilling Channels for 2 Coat Spin Units (2-1 COT and 2-2 TCT)
 - b. 2 Chilling Channel for 2 Develop Units (2-3 DEV and 2-4 DEV)
 - c. 3 Chilling Channel for 3 CPL/Chill Plate Process Station Units

- J. Power Transformer AC Cabinet : 208VAC, 3 Phases, 50/60Hz
- K. Software Options
 - a. Software Version : 1.18
 - b. Please refer to “Intellectual Property Responsibilities” at “Article 7. Important Notice”.
- L. Safety Regulation Compliance : TEL S2-93 Safety Specification
- M. Utility connection Position : Bottom/Back Side

7. Important Notice

- 2) This Document could contain typographical errors or technical inaccuracies.
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